

TITLE OF THE INVENTION: WAFER GRINDING METHODS

Abstract

A wafer grinding method comprises: providing a wafer base comprising a front side and a back side, wherein the front side comprises a solder ball area and an annular peripheral area surrounding the solder ball area; forming a patterned photoresist layer on the front side of the wafer base, wherein the patterned photoresist layer at least partially covers the annular peripheral area but exposes the solder ball area; forming solder balls on the solder ball area; attaching a back grinding tape on the front side to cover both the solder ball area and the annular peripheral area; and performing a back grinding process on the back side of the wafer base.

[Fig. 2C]